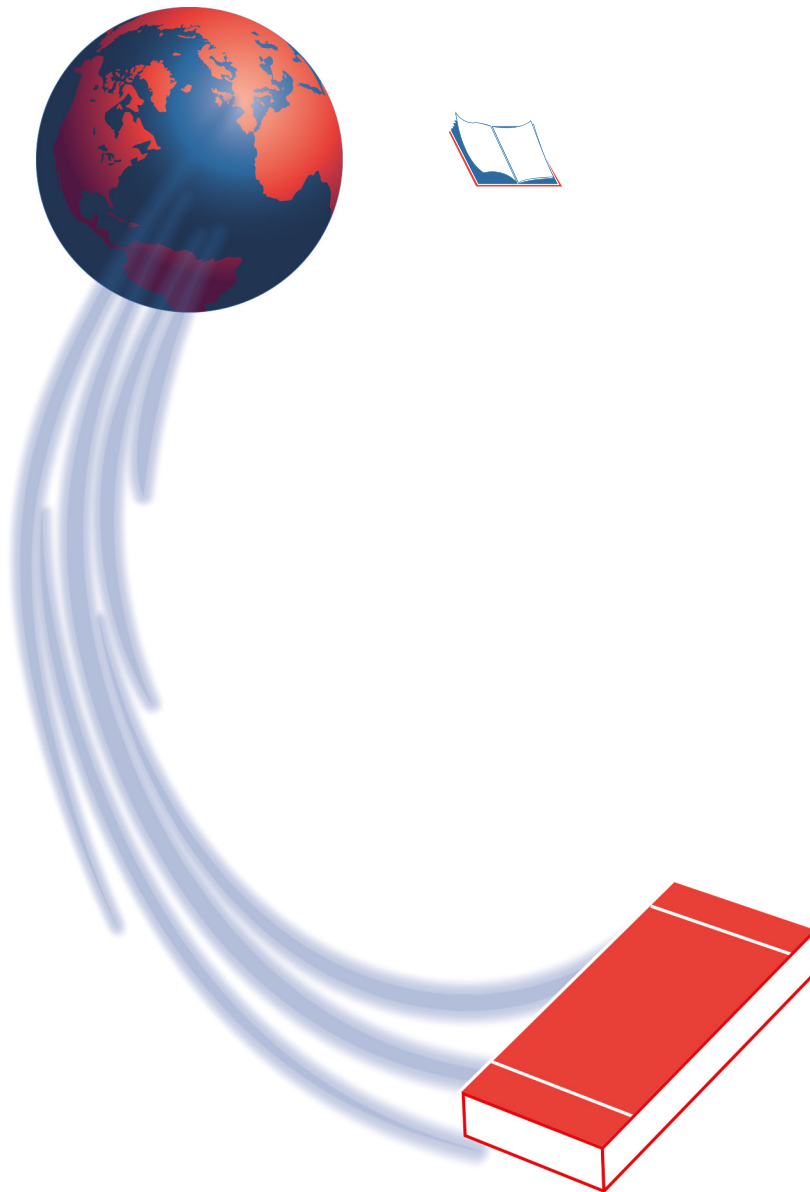


SMD TERMINATIONS



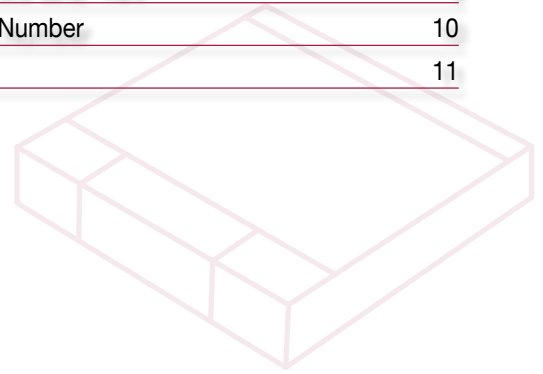
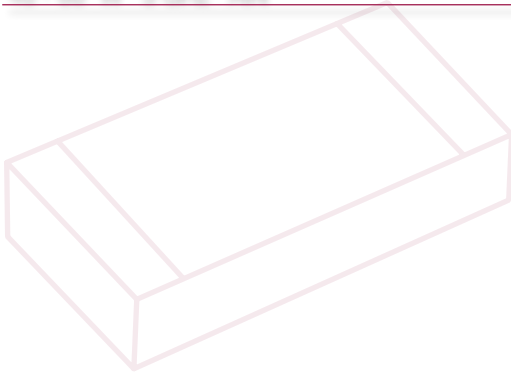


For Power Amplifiers, Couplers, Combiners & Isolators

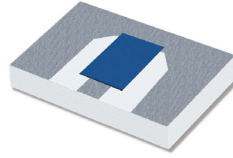
- ⇒ Easy soldering on PCB
- ⇒ Sizes 0606 to 5050
- ⇒ 3 W - 200 W
- ⇒ Up to 12 GHz
- ⇒ Contact finition Tin over Nickel Barrier

SMD Terminations

3 W 12GHz Al ₂ O ₃	3	40 - 120* W 2.5 GHz AlN	8
10 W 3 GHz AlN	4	100 - 200* W 3.5 GHz AlN	9
10 - 30* W 4.4 GHz Al ₂ O ₃	5	Search by Part Number	10
30 - 60* W 4.4 GHz AlN	6	Notes	11
40 - 60* W 3 GHz AlN	7		



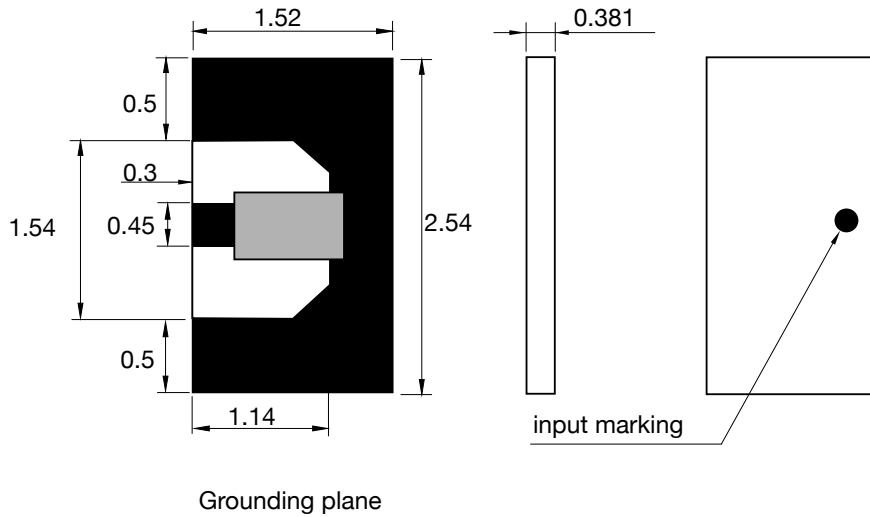
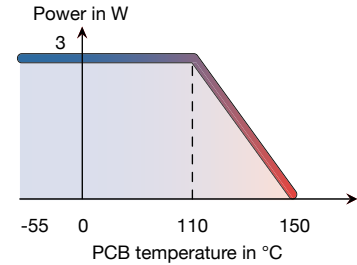
3 W 12GHz Al₂O₃



Standards
NF C 96-315
MIL-DTL-39030



Substrate	Al ₂ O ₃
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	PtAg
Size	1006



SMD Terminations



Dimensions in mm

[Return to Search by Part Number](#)

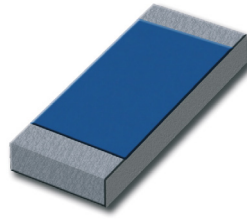
P/N	Frequency (GHz)	Power (W)	Impedance (Ω ± 5%)	Max VSWR
46-0030	12	3	50	1.25

mm	inch
0.30	0.012
0.38	0.015
0.45	0.018
0.50	0.020
1.14	0.044
1.52	0.060
2.54	0.100

10 W 3 GHz AIN

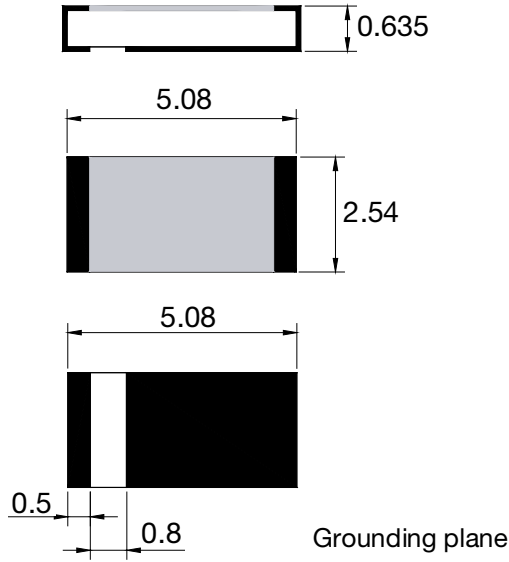
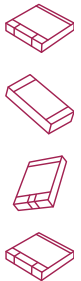
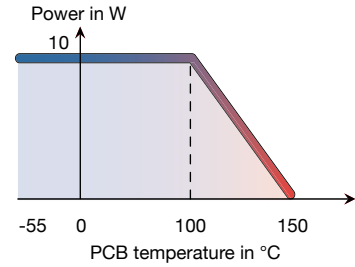


Standards
NF C 96-315
MIL-DTL-39030



SMD Terminations

Substrate	AIN
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	Tin over Nickel barrier
Size	2010



Dimensions in mm

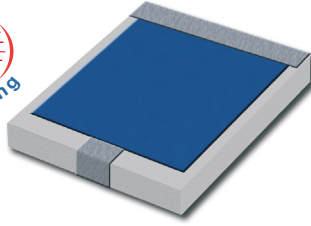
[Return to Search by Part Number](#)

P/N	Frequency (GHz)	Power (W)	Impedance ($\Omega \pm 5\%$)	Max VSWR
45-0040S	3	10	50	1.20

mm	inch
0.5	0.020
0.635	0.025
0.8	0.031
2.54	0.100
5.08	0.200

Available on Tap and Reel Packaging

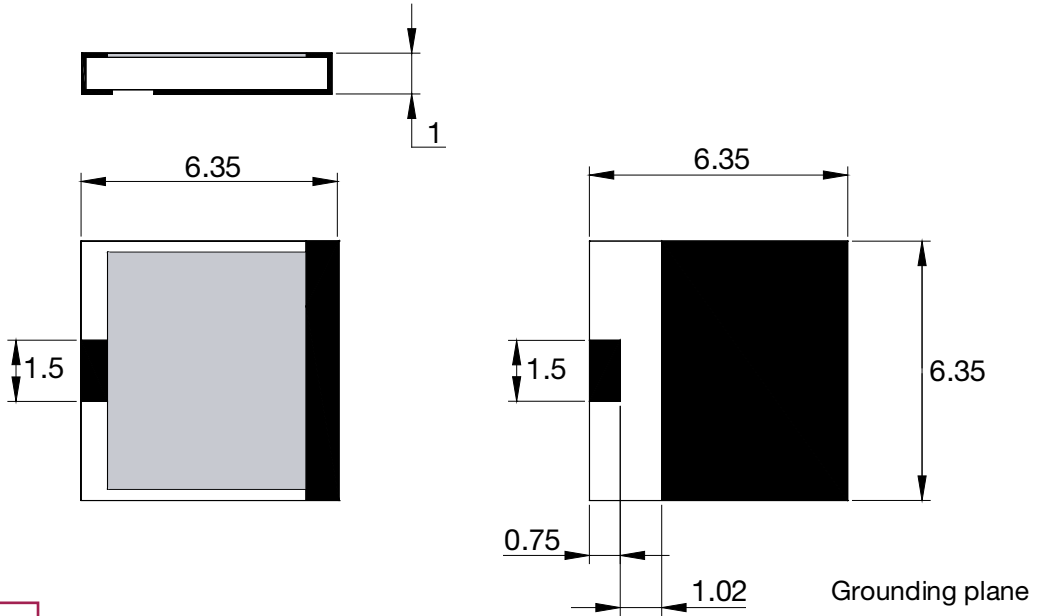
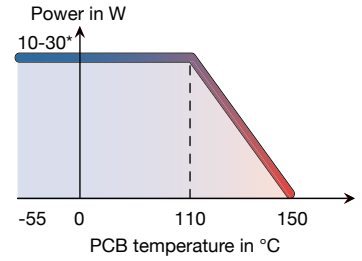
10 - 30* W 4.4 GHz Al₂O₃



Standards
NF C 96-315
MIL-DTL-39030



Substrate	Al ₂ O ₃
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	Tin over Nickel barrier
Size	2525



Dimensions in mm

SMD Terminations

[Return to Search by Part Number](#)

P/N	Frequency (GHz)	Power (W)	Impedance (Ω ± 5%)	Max VSWR
46-0010S	4.4	30	50	1.25**

mm	inch
0.75	0.030
1	0.039
1.02	0.040
1.5	0.059
6.35	0.250

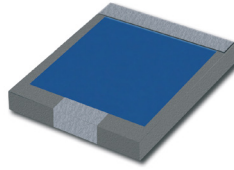
* **IMPORTANT NOTE FOR POWER DISSIPATION**
 10 W : When mounted on PCB 0.8 mm thick Sn 35 μ plated with 48 holes Ø 0.5 mm filled with Sn96Ag4 solder.
 30 W : When directly soldered on 4.5 mm Cu cylinder acting as a thermal drain.
 ** VSWR ≤ 1.15 at 2.2 GHz

Available on Tap and Reel Packaging

30 - 60* W 4.4 GHz AIN

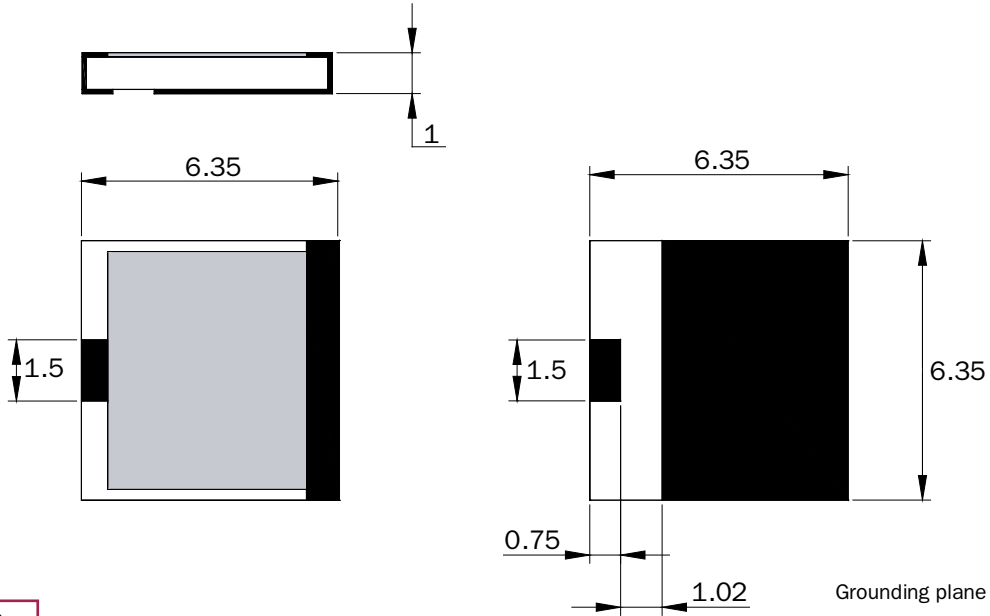
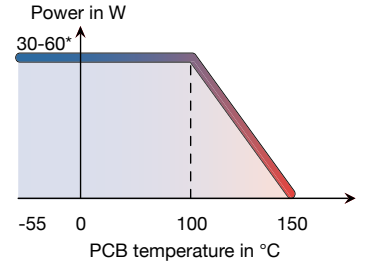


Standards
NF C 96-315
MIL-DTL-39030

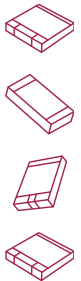


SMD Terminations

Substrate	AIN
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	Tin over Nickel barrier
Size	2525



Dimensions in mm



[Return to Search by Part Number](#)

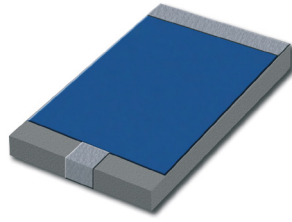
P/N	Frequency (GHz)	Power (W)	Impedance ($\Omega \pm 5\%$)	Max VSWR
45-0010S	4.4	60	50	1.25**

mm	inch
0.75	0.033
1	0.039
1.02	0.040
1.5	0.059
6.35	0.250

* **IMPORTANT NOTE FOR POWER DISSIPATION**
 30 W : When mounted on PCB 0.8 mm thick Sn 35 μ plated with 48 via holes \varnothing 0.5 mm filled with Sn96Ag4 solder.
 60 W : When directly soldered on \varnothing 4.5 mm Cu cylinder acting as a thermal drain.
 ** VSWR \leq 1.15 at 2.2 GHz

Available on Tap and Reel Packaging

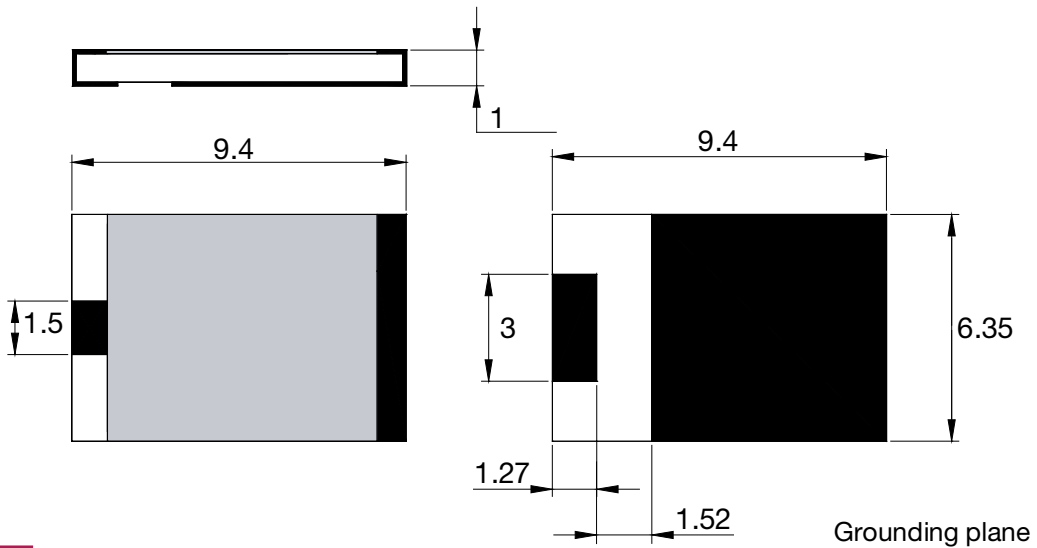
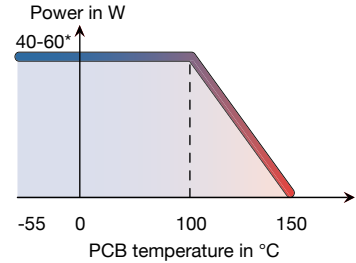
40 - 60* W 3 GHz AIN



Standards
NF C 96-315
MIL-DTL-39030



Substrate	AIN
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	Tin over Nickel barrier
Size	3725



SMD Terminations



Dimensions in mm

[Return to Search by Part Number](#)

P/N	Frequency (GHz)	Power (W)	Impedance ($\Omega \pm 5\%$)	Max VSWR
45-0012S	3	60	50	1.25

mm	inch
1	0.039
1.27	0.050
1.5	0.059
1.52	0.060
3	0.118
6.35	0.250
9.4	0.370

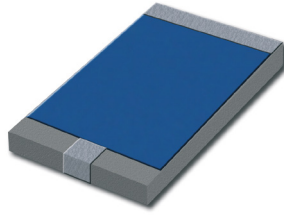
* **IMPORTANT NOTE FOR POWER DISSIPATION**
 40 W : When mounted on PCB 0.8 mm thick Sn 35 μ plated with 64 via holes \varnothing 0.5 mm filled with Sn96Ag4 solder.
 60 W : When directly soldered on \varnothing 4.5 mm Cu cylinder acting as a thermal drain.

Available on Tap and Reel Packaging

40 - 120* W 2.5 GHz AIN

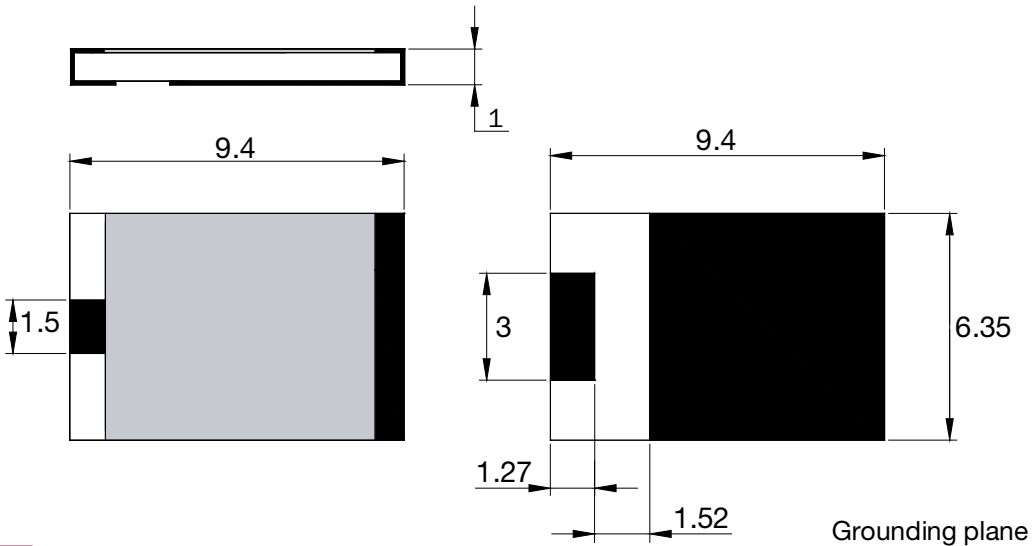
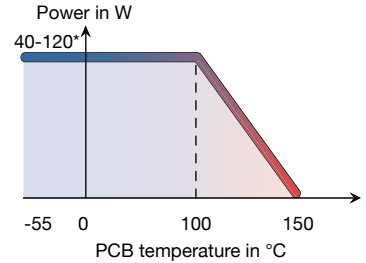


Standards
NF C 96-315
MIL-DTL-39030



SMD Terminations

Substrate	AIN
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	Tin over Nickel barrier
Size	3725



Dimensions in mm

Grounding plane

[Return to Search by Part Number](#)

P/N	Frequency (GHz)	Power (W)	Impedance ($\Omega \pm 5\%$)	Max VSWR
45-0011S	2.5	120	50	1.25

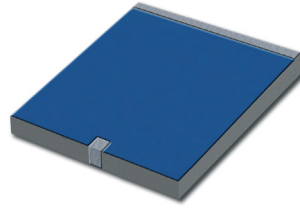
mm	inch
1	0.039
1.27	0.050
1.5	0.059
1.52	0.060
3	0.118
6.35	0.250
9.4	0.370

*** IMPORTANT NOTE FOR POWER DISSIPATION**

40 W : When mounted on PCB 0.8 mm thick Sn 35 μ plated with 64 via holes \varnothing 0.5 mm filled with Sn96Ag4 solder.
120 W : When directly soldered on \varnothing 6.35 mm Cu cylinder acting as a thermal drain.

Available on Tap and Reel Packaging

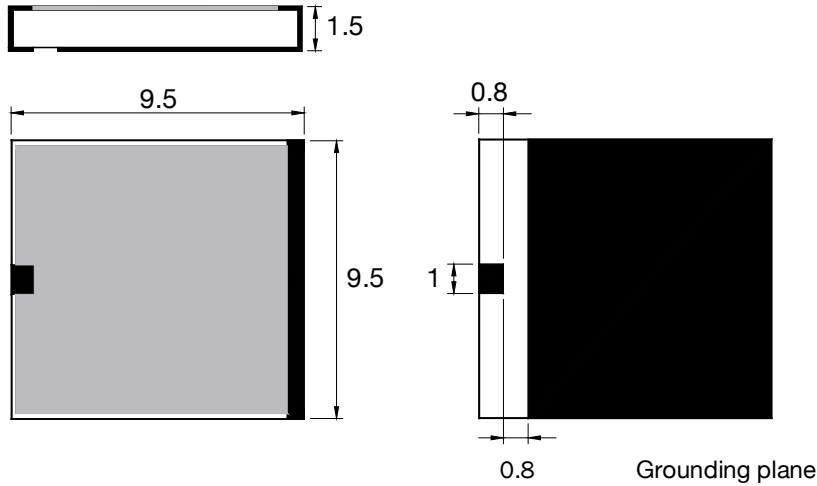
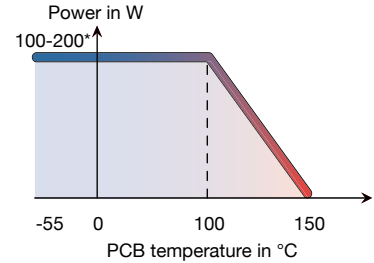
100 - 200* W 3.5 GHz AIN



Standards
NF C 96-315
MIL-DTL-39030



Substrate	AIN
Resistive film	Thick film
Protection film	Epoxy
Contacts finition	Tin over Nickel barrier
Size	3737



Dimensions in mm

SMD Terminations



Return to Search by Part Number

P/N	Frequency (GHz)	Power (W)	Impedance ($\Omega \pm 5\%$)	Max VSWR
45-0025S	3.5	200	50	1.30

mm	inch
0.8	0.031
1	0.039
1.5	0.059
9.5	0.374

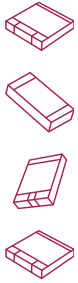
* **IMPORTANT NOTE FOR POWER DISSIPATION**
 100 W : When mounted on PCB 0.8 mm thick Sn 35 μ plated with 120 via holes \varnothing 0.5 mm filled with Sn96Ag4 solder.
 200 W : When directly soldered on \varnothing 6.35 mm Cu cylinder acting as a thermal drain.

Available on Tap and Reel Packaging

Search by Part Number

Part Number	Pages
45-0010S	A6
45-0011S	A8
45-0012S	A7
45-0025S	A9
45-0040S	A4
46-0010S	A5
46-0030	A3

SMD Terminations





Notes

SMD Terminations



